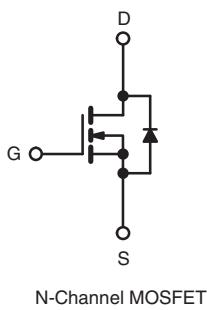
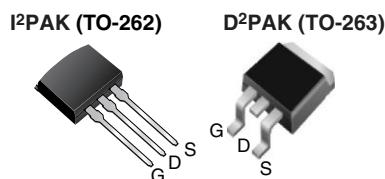


Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	60	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10$ V	0.20
Q_g (Max.) (nC)	11	
Q_{gs} (nC)	3.1	
Q_{gd} (nC)	5.8	
Configuration	Single	



FEATURES

- Halogen-free According to IEC 61249-2-21
- Definition
- Advanced Process Technology
- Surface Mount (IRFZ14S, SiHFZ14S)
- Low-Profile Through-Hole (IRFZ14L, SiHFZ14L)
- 175 °C Operating Temperature
- Fast Switching
- Compliant to RoHS Directive 2002/95/EC



RoHS*
COMPLIANT
HALOGEN
FREE
Available

DESCRIPTION

Third generation Power MOSFETs from Vishay utilize advanced processing techniques to achieve extremely low on resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that Power MOSFETs are well known for, provides the designer with an extremely efficient reliable device for use in a wide variety of applications.

The D²PAK is a surface mount power package capable of accommodating die sizes up to HEX-4. It provides the highest power capability and lowest possible on-resistance in any existing surface mount package. The D²PAK is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface mount application.

The through-hole version (IRFZ14L, SiHFZ44L) is available for low profile applications.

ORDERING INFORMATION

Package	D²PAK (TO-263)	D²PAK (TO-263)	I²PAK (TO-262)
Lead (Pb)-free and Halogen-free	SiHFZ14S-GE3	SiHFZ14STR-GE3 ^a	SiHFZ14L-GE3
Lead (Pb)-free	IRFZ14SPbF	IRFZ14STRLPbF ^a	IRFZ14LPbF
	SiHFZ14S-E3	SiHFZ14STL-E3 ^a	SiHFZ14L-E3

Note

a. See device orientation.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	10 7.2	A
Pulsed Drain Current ^a	I_{DM}	40	
Linear Derating Factor		0.29	W/°C
Single Pulse Avalanche Energy ^b	E_{AS}	47	mJ
Maximum Power Dissipation	P_D	43	W
Maximum Power Dissipation (PCB Mount) ^e		3.7	
Peak Diode Recovery dV/dt^c	dV/dt	4.5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{Stg}	- 55 to + 175	°C
Soldering Recommendations (Peak Temperature)	for 10 s	300 ^d	

Notes

b. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

c. $V_{DD} = 25$ V, starting $T_J = 25$ °C, $L = 548$ μ H, $R_g = 25$ Ω , $I_{AS} = 10$ A (see fig. 12).

d. $I_{SD} \leq 10$ A, $dI/dt \leq 90$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 175$ °C.

e. 1.6 mm from case.

f. When mounted on 1" square PCB (FR-4 or G-10 material).

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient (PCB Mount) ^a	R_{thJA}	-	40	$^{\circ}\text{C}/\text{W}$
Maximum Junction-to-Case (Drain)	R_{thJC}	-	3.5	

Note

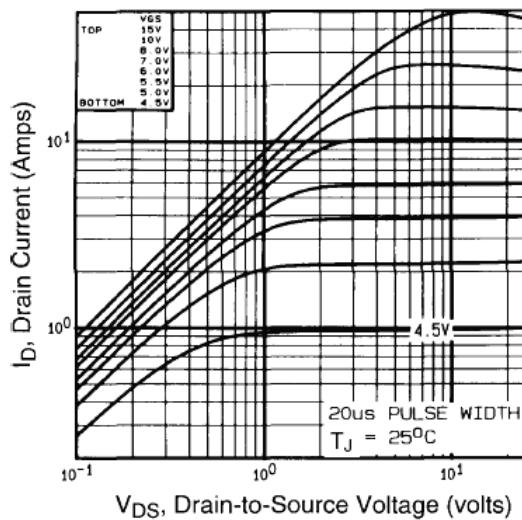
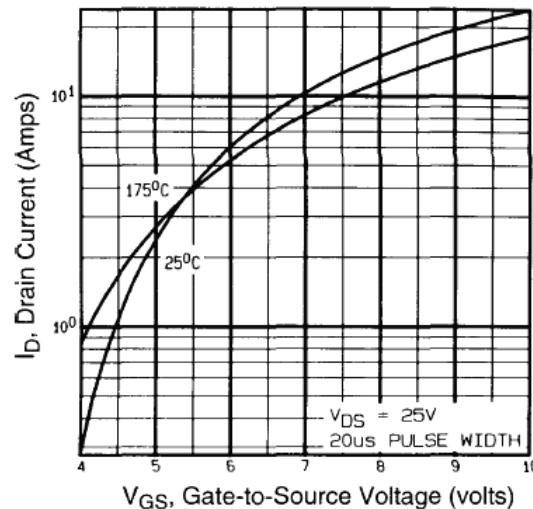
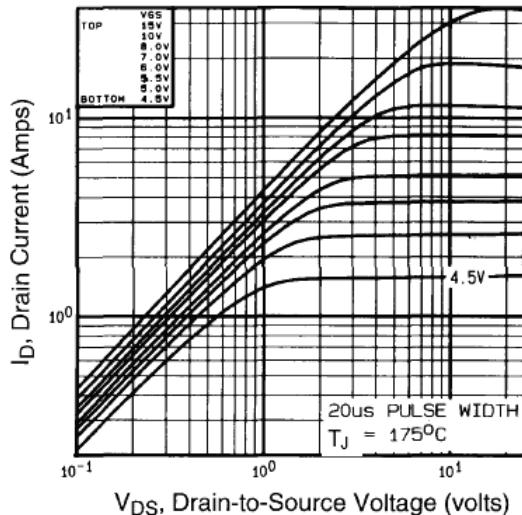
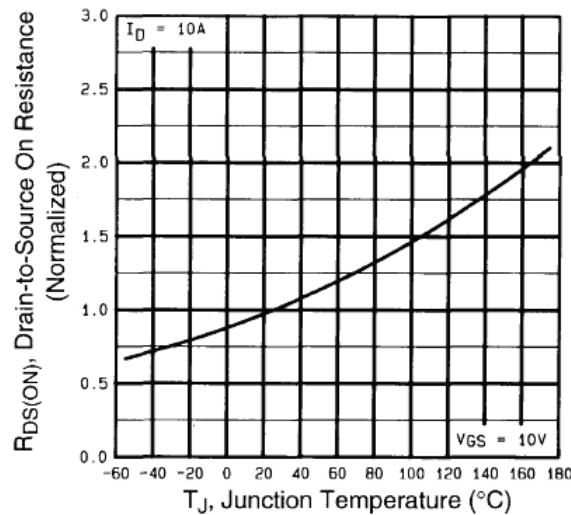
a. When mounted on 1" square PCB (FR-4 or G-10 material).

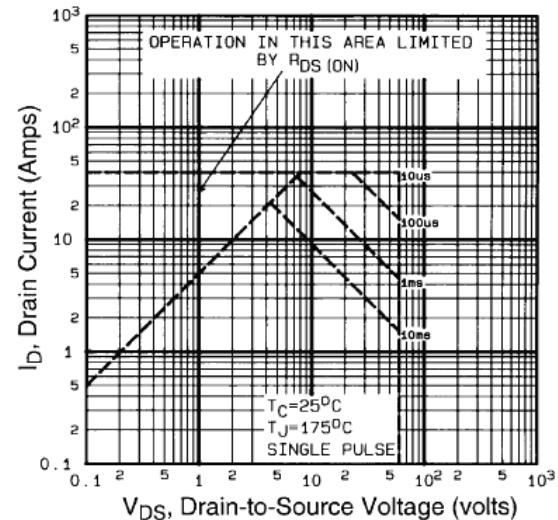
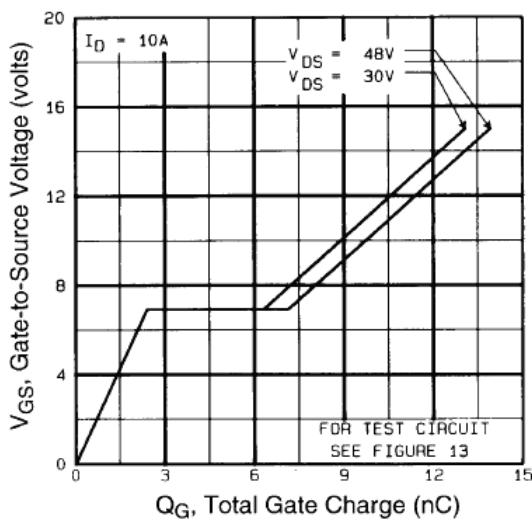
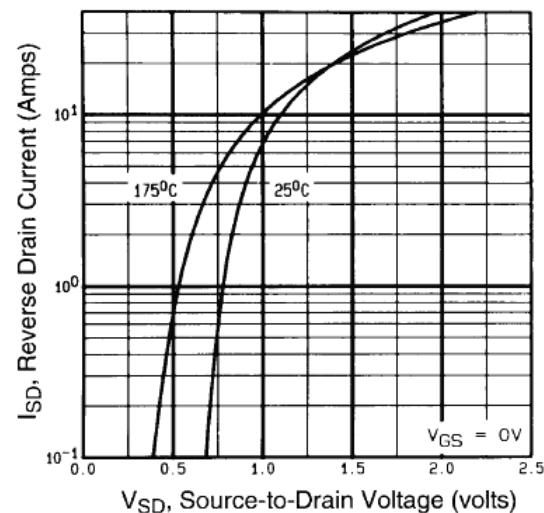
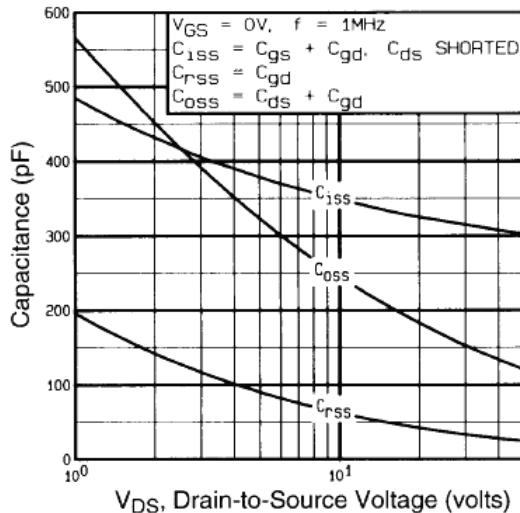
SPECIFICATIONS ($T_J = 25 \text{ }^{\circ}\text{C}$, unless otherwise noted)

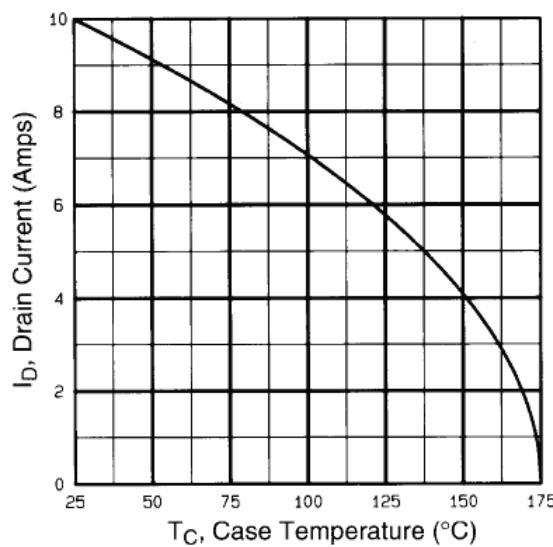
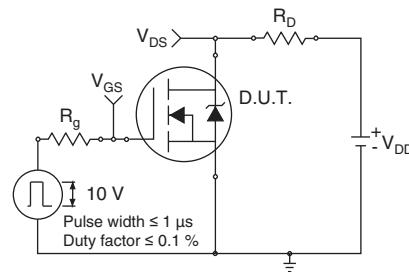
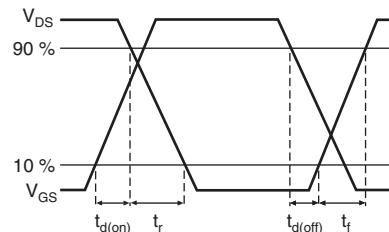
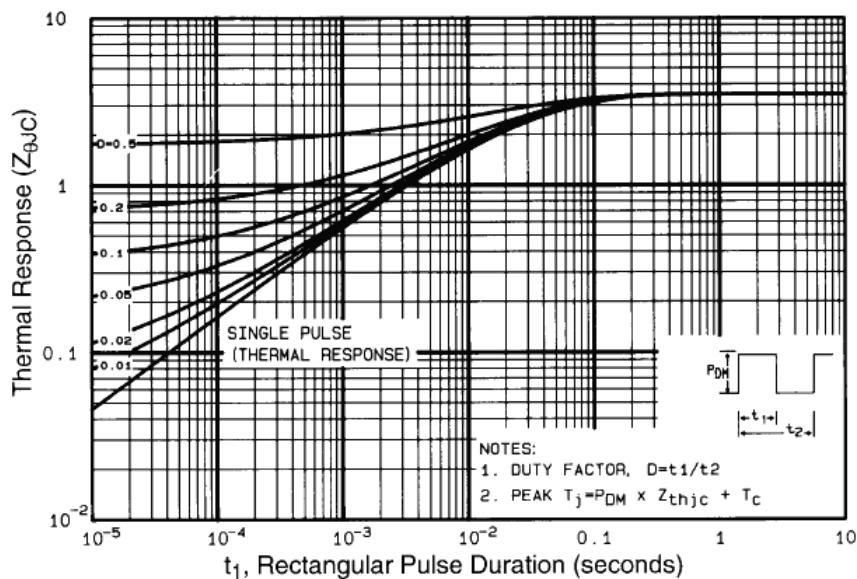
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0$, $I_D = 250 \mu\text{A}$		60	-	-	V	
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25 \text{ }^{\circ}\text{C}$, $I_D = 1 \text{ mA}$		-	0.063	-	V/C	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$		2.0	-	4.0	V	
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 60 \text{ V}$, $V_{GS} = 0 \text{ V}$		-	-	25	μA	
		$V_{DS} = 48 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 150 \text{ }^{\circ}\text{C}$		-	-	250		
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$	$I_D = 6.0 \text{ A}^b$	-	-	0.2	Ω	
Forward Transconductance	g_{fs}	$V_{DS} = 25 \text{ V}$, $I_D = 6.0 \text{ A}^b$		2.4	-	-	S	
Dynamic								
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1.0 \text{ MHz}$, see fig. 5		-	300	-	pF	
Output Capacitance	C_{oss}			-	160	-		
Reverse Transfer Capacitance	C_{rss}			-	29	-		
Total Gate Charge	Q_g	$V_{GS} = 10 \text{ V}$	$I_D = 10 \text{ A}$, $V_{DS} = 48 \text{ V}$, see fig. 6 and 13 ^b	-	-	11	nC	
Gate-Source Charge	Q_{gs}			-	-	3.1		
Gate-Drain Charge	Q_{gd}			-	-	5.8		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 30 \text{ V}$, $I_D = 10 \text{ A}$, $R_g = 24 \Omega$, $R_D = 2.7 \Omega$, see fig. 10 ^b		-	10	-	ns	
Rise Time	t_r			-	50	-		
Turn-Off Delay Time	$t_{d(off)}$			-	13	-		
Fall Time	t_f			-	19	-		
Internal Source Inductance	L_s	Between lead, and center of die contact		-	7.5	-	nH	
Drain-Source Body Diode Characteristics								
Continuous Source-Drain Diode Current	I_s	MOSFET symbol showing the integral reverse p - n junction diode		-	-	10	A	
Pulsed Diode Forward Current ^a	I_{SM}			-	-	40		
Body Diode Voltage	V_{SD}	$T_J = 25 \text{ }^{\circ}\text{C}$, $I_s = 10 \text{ A}$, $V_{GS} = 0 \text{ V}^b$		-	-	1.6	V	
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25 \text{ }^{\circ}\text{C}$, $I_F = 10 \text{ A}$, $dl/dt = 100 \text{ A}/\mu\text{s}^b$		-	70	140	ns	
Body Diode Reverse Recovery Charge	Q_{rr}			-	200	400	μC	
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_s and L_D)						

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width $\leq 300 \mu\text{s}$; duty cycle $\leq 2 \%$.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 1 - Typical Output Characteristics

Fig. 3 - Typical Transfer Characteristics

Fig. 2 - Typical Output Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature




Fig. 9 - Maximum Drain Current vs. Case Temperature

Fig. 10a - Switching Time Test Circuit

Fig. 10b - Switching Time Waveforms

Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

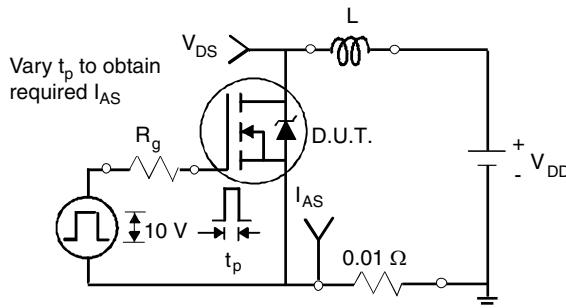


Fig. 12a - Unclamped Inductive Test Circuit

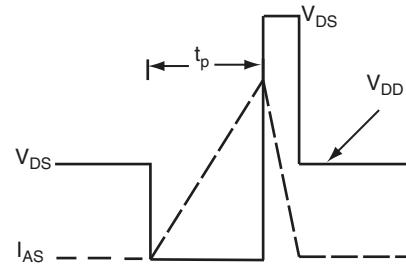


Fig. 12b - Unclamped Inductive Waveforms

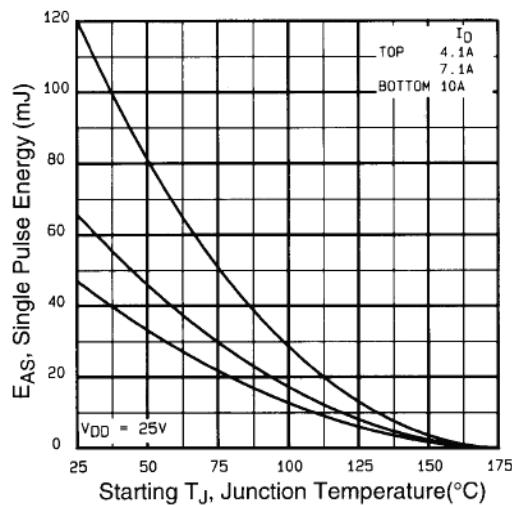


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

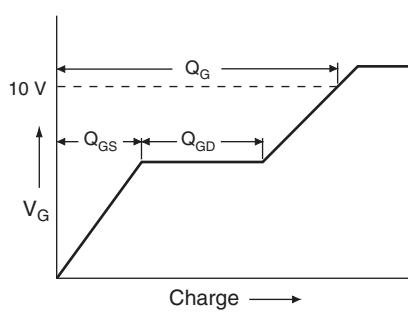


Fig. 13a - Basic Gate Charge Waveform

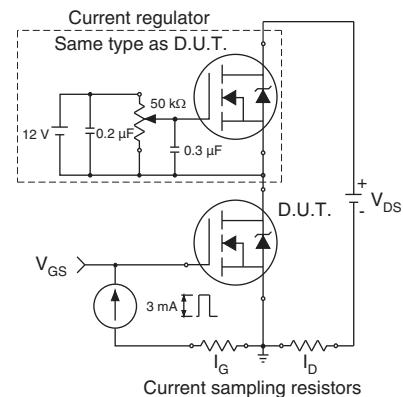
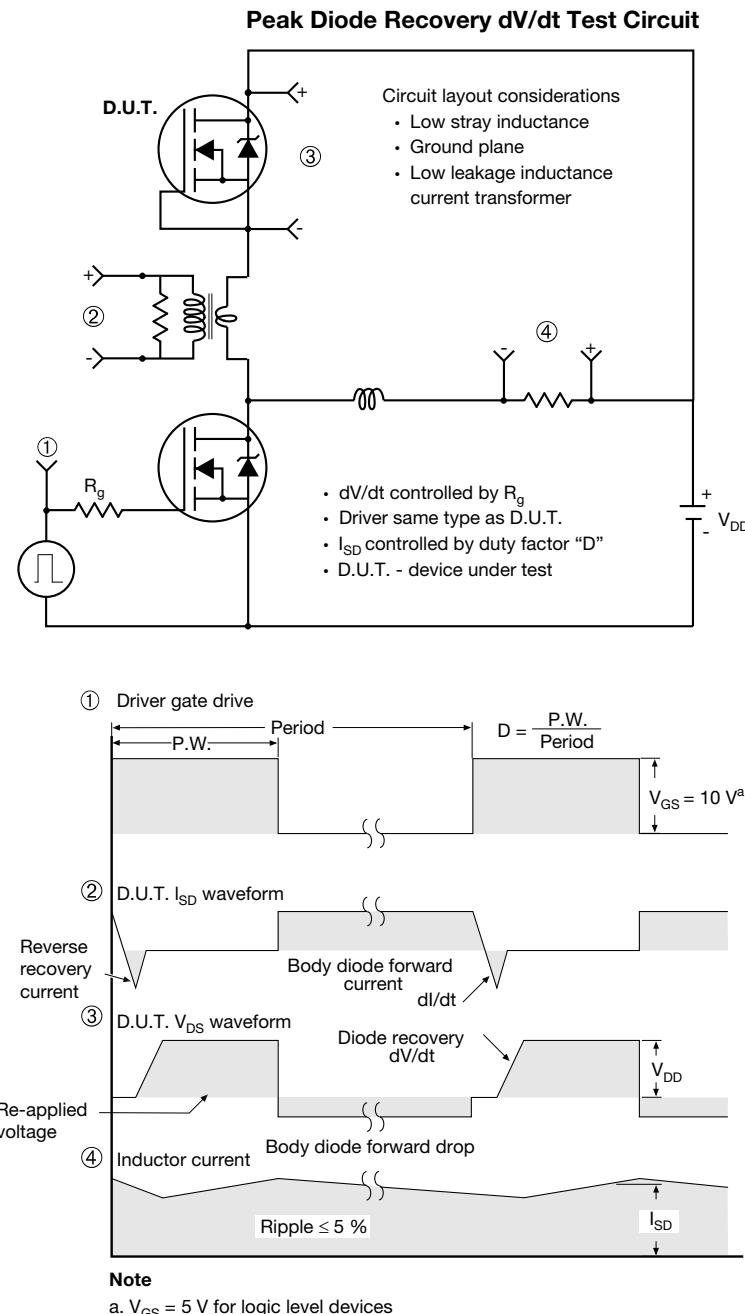
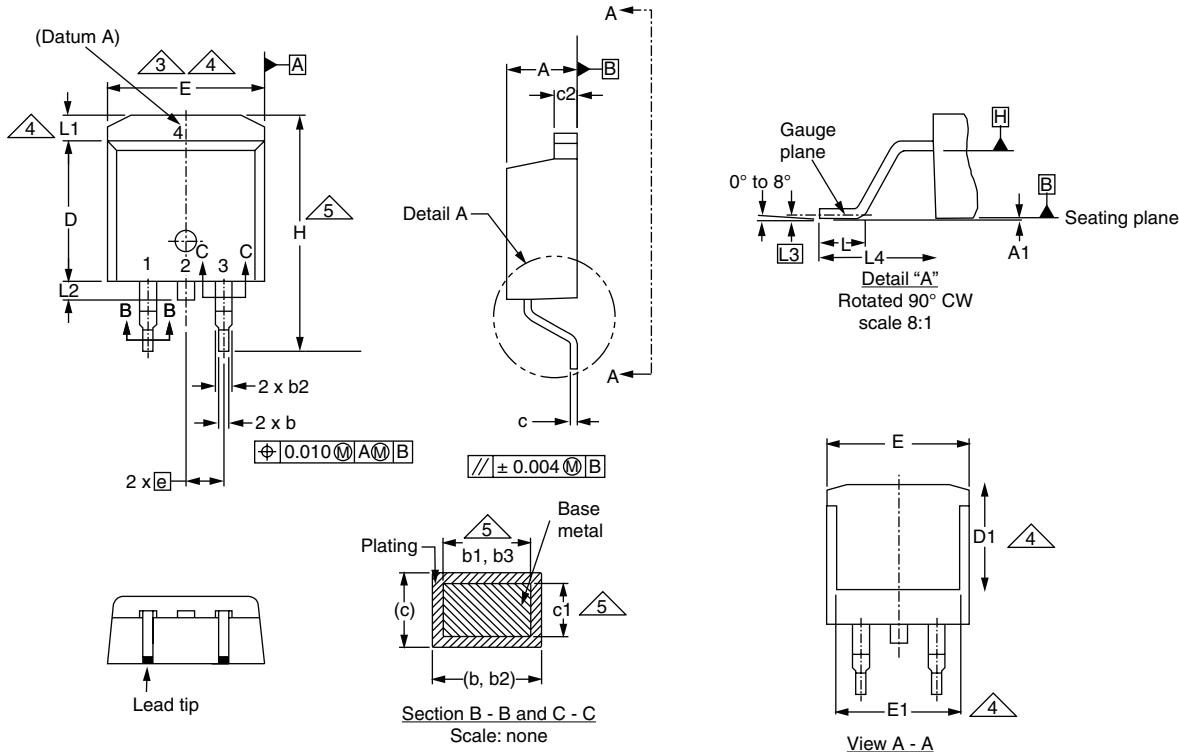


Fig. 13b - Gate Charge Test Circuit


Fig. 14 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?90365.

TO-263AB (HIGH VOLTAGE)



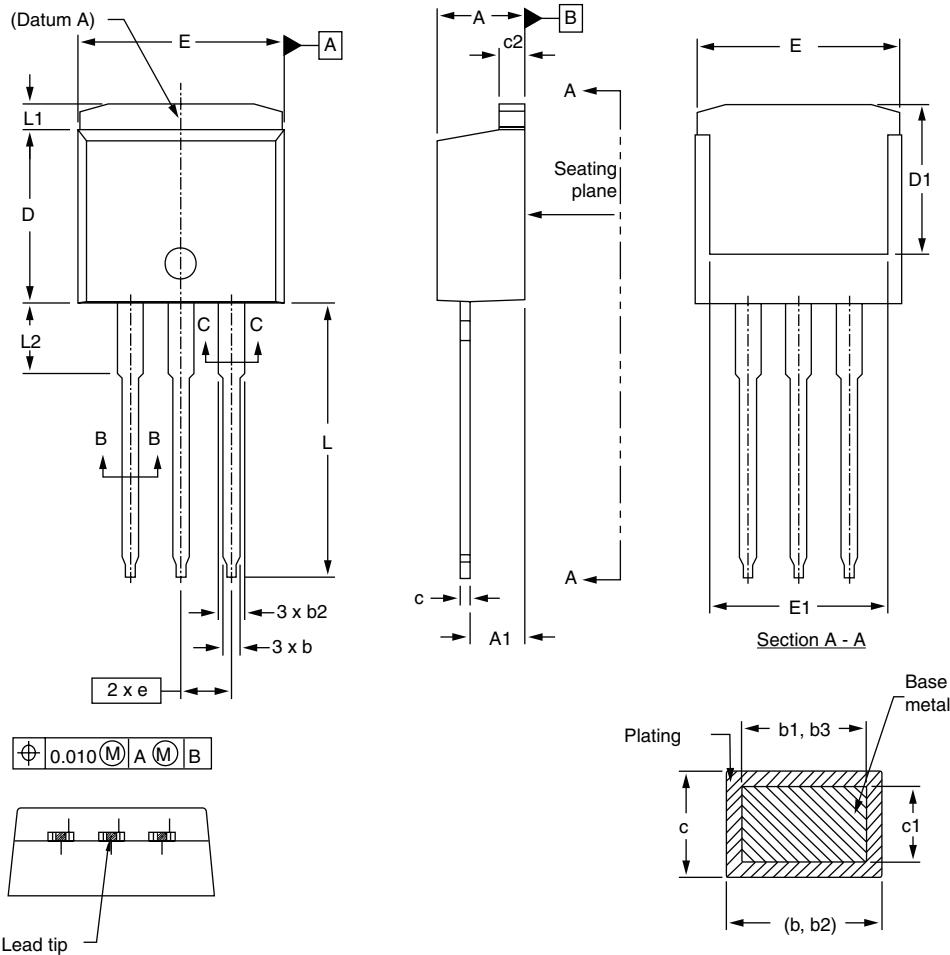
	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.

I²PAK (TO-262) (HIGH VOLTAGE)



Section B - B and C - C

Scale: None

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	2.03	3.02	0.080	0.119
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065

ECN: S-82442-Rev. A, 27-Oct-08

DWG: 5977

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm per side. These dimensions are measured at the outmost extremes of the plastic body.
3. Thermal pad contour optional within dimension E, L1, D1, and E1.
4. Dimension b1 and c1 apply to base metal only.

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D	8.38	9.65	0.330	0.380
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
L	13.46	14.10	0.530	0.555
L1	-	1.65	-	0.065
L2	3.56	3.71	0.140	0.146

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